



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

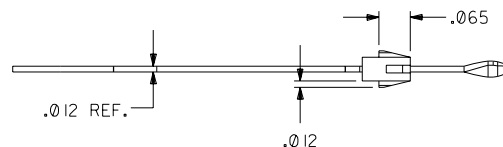
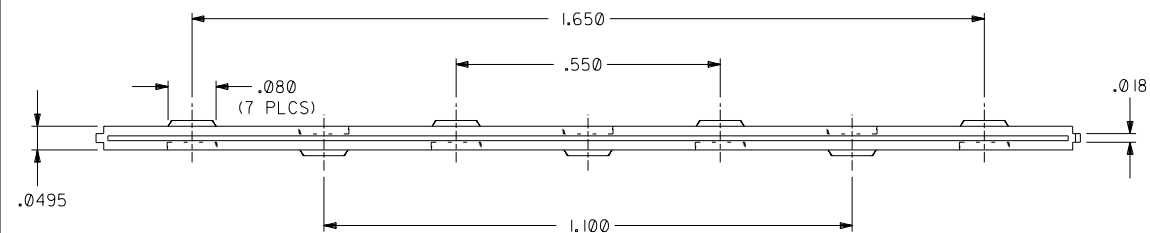
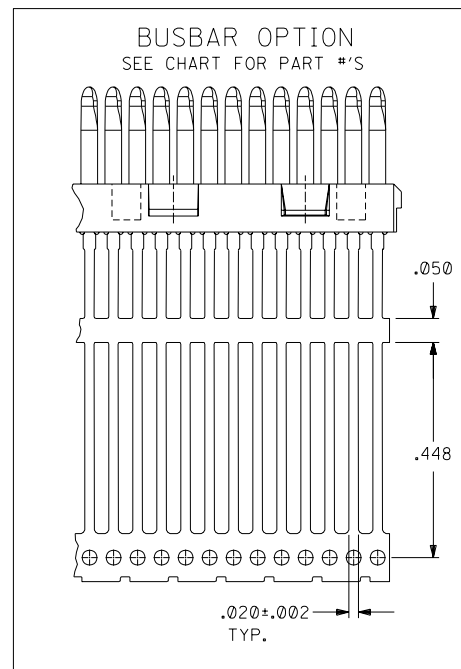
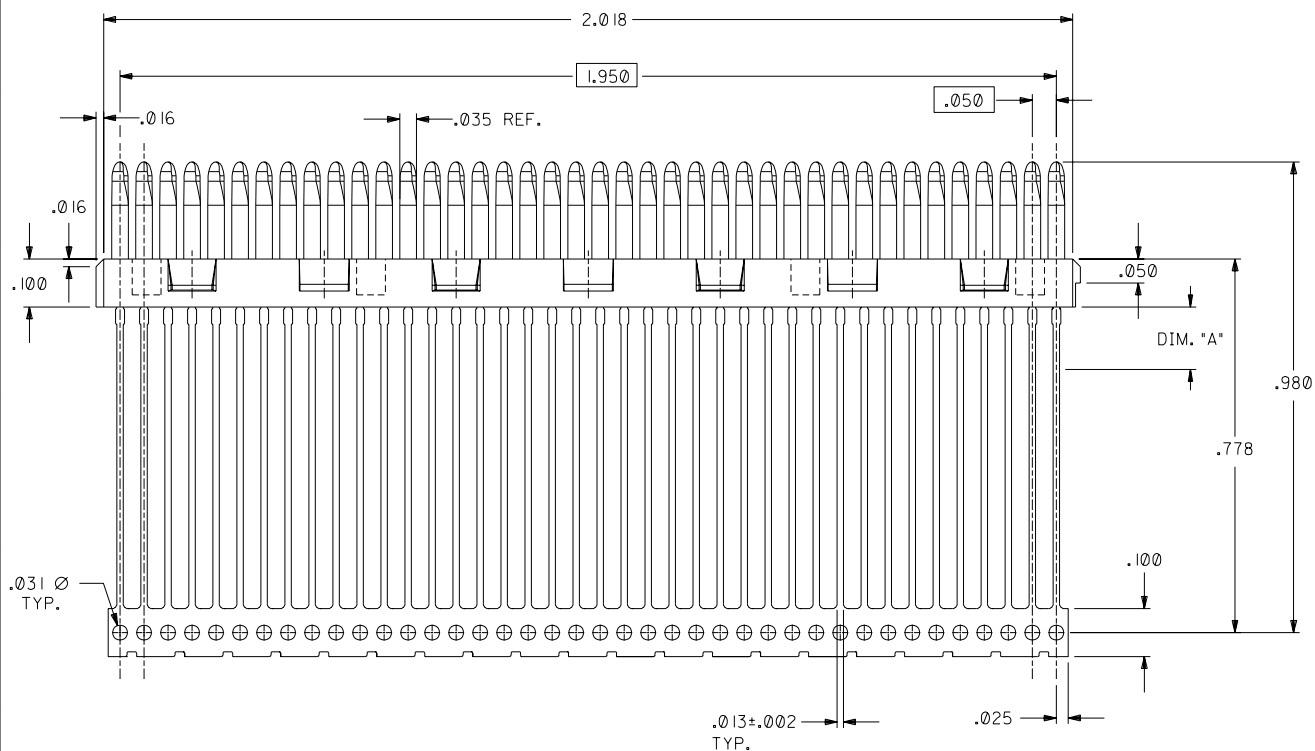
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NOTE FOR LEAD FREE CONVERSION:
 THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO ROHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.

NOTES

- 1) INSULATOR: GLASS FILLED POLYMER, U.L. 94 V-0, COLOR: BLACK.
 TERMINAL: PHOSPHOR BRONZE, .012" THICK.
 PLATING: .000030/(0.000762) MINIMUM GOLD IN CONTACT AREA OVER NICKEL UNDERPLATE. SEE CHART FOR SOLDER TAIL PLATING DESCRIPTIONS.
- 2) FOR PART #'s & PLATING OPTIONS, SEE CHART.
- 3) PARTS CONFORM TO PRODUCT SPECIFICATION PS-71626.
- 4) PACKAGING SPECIFICATION PK-70873-0233 APPLIES.



B	LEADFREE ECN# UCF2004-1998 DMORGAN 04/04/14
A3	ADDED OPTION PER UDT1999-0961
A2	ADDED OPTION PER ECN U6-0586 DRS 11/10/95
A1	ADDED OPTION PER ECN U6-0095 DRS 07/26/95
A	Initial Release PER ECN# U4-0843 MOS 7/11/94

70984-4009	SDA-70984-4009	NO	.130	.000100/(0.00254) MINIMUM TIN OVER NICKEL UNDERPLATE.
70984-4008	SDA-70984-4008	YES		.000200/(0.00508) MINIMUM TIN OVER .000075/(0.0019) MINIMUM NICKEL UNDERPLATE.
70984-4003	SDA-70984-4003	YES		.000050/(0.00127) MINIMUM NICKEL.
051-25-1020	SDA-70984-4000	NO		.000100/(0.00254) MINIMUM TIN OVER NICKEL UNDERPLATE.
PART NUMBER	ENGINEERING NUMBER	BUSBAR OPTION	DIM. "A"	PLATING (TERMINATION END ONLY)

DIMENSIONS SHOWN (METRIC) INCH		▽ = 0		= 0		REVISE ONLY ON CAD SYSTEM	
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°		TITLE		40ck+ LFH INSERT MOLDED CONTACTS SALES DETAIL		SHEET NO. DATE U.S.A. 1 OF 1 07/11/94	
3 PLACE ± .010 ---		PART NO.		MOLEX INCORPORATED		DRWG. NO.	
2 PLACE ± --- ±		SEE CHART		SDA-70984-4***			
1 PLACE --- ±		APPROD. BY MOS		FILE NAME 570984X4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
DRAWN BY GF		CHK'D BY DKS		SCALE 5: 1		DIV. CD	